

Data and signal line chokes

Common-mode chokes, ring core
4.7 ... 68 mH, 200 ... 700 mA, +40 °C

Series/Type: **B82720H15**

Date: December 2023

Rated voltage 42 V AC / 80 V DC
Rated current 200 ... 700 mA / +40 °C
Nominal inductance 4.7 ... 68 mH

Construction

- Current-compensated ring core double choke
- Ferrite core
- Polycarbonate case (UL 94 V-0)
- Polyurethane potting (UL 94 V-0)



Features

- Suitable for automatic insertion
- Suitable for wave soldering
- RoHS-compatible

Applications

- Telecom switching systems
- Terminal systems
- Measuring and control lines

Terminals

- Base material CuNi18Zn20
- Layer composition Ni, Sn
- Hot-dipped
- Lead spacing 10 × 7.5 (mm)

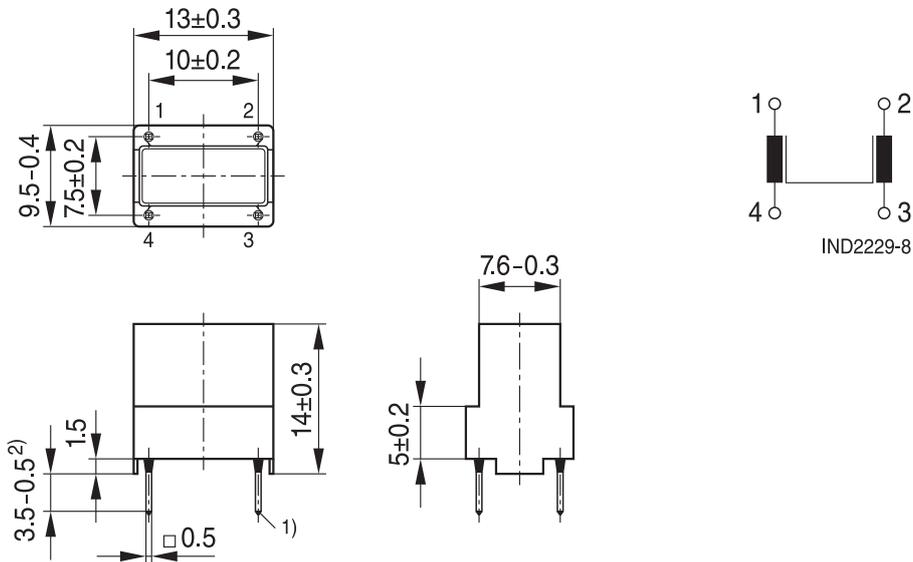
Marking

- Product brand (EPCOS), ordering code, rated inductance, rated current, date of manufacture (YYWWD)

Delivery mode

- Cardboard box

Dimensional drawing and pin configuration



IND2229-8

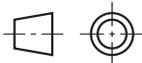
IND2198-D-E

- 1) Tin tips permissible
- 2) Dimension does not include tin tip

Tolerances to ISO 2768-c / ISO 8015.

Size ISO 14405 $\text{\textcircled{E}}$

All dimensions in mm



IND2200-F-E

Technical data and measuring conditions

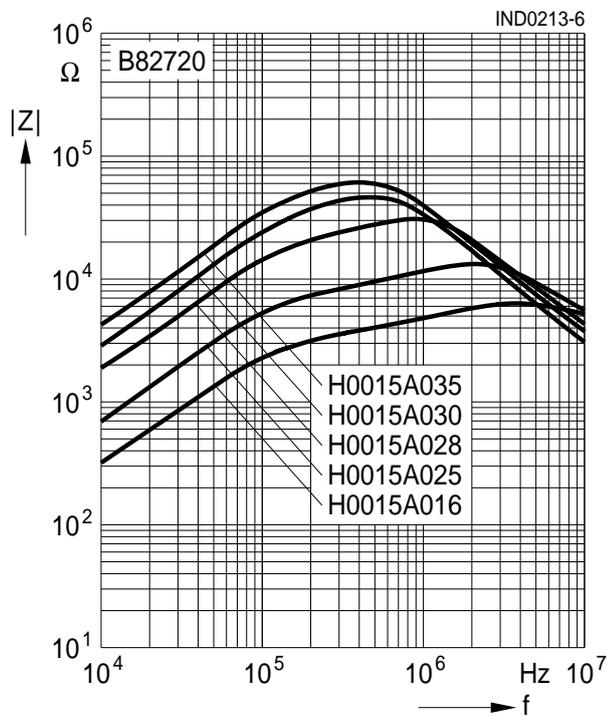
Rated voltage V_R	42 V AC (50/60 Hz) / 80 V DC
Rated temperature T_R	+40 °C
Rated current I_R	Referred to 50 Hz and rated temperature
Nominal inductance L_R	Measured with Agilent 4284A at 10 kHz, 0.1 mA, +20 °C Inductance is specified per winding.
Inductance tolerance	-30%/+50% at +20 °C
Inductance decrease $\Delta L/L_0$	< 10% at DC magnetic bias with I_R , +20 °C
Stray inductance $L_{\text{stray,typ}}$	Measured with Agilent 4284A at 10 kHz, 5 mA, +20 °C, typical values
DC resistance R_{typ}	Measured at +20 °C, typical values, specified per winding
Solderability (lead-free)	Sn96.5Ag3.0Cu0.5: +(245 ±5) °C, (3 ±0.3) s Wetting of soldering area ≥ 95% (to IEC 60068-2-20, test Ta)
Resistance to soldering heat (wave soldering)	+(260 ±5) °C, (10 ±1) s (to IEC 60068-2-20, test Tb)
Climatic category	40/125/56 (to IEC 60068-1)
Storage conditions (packaged)	-25 °C ... +40 °C, ≤ 75% RH
Weight	Approx. 2.1 g

Characteristics and ordering codes

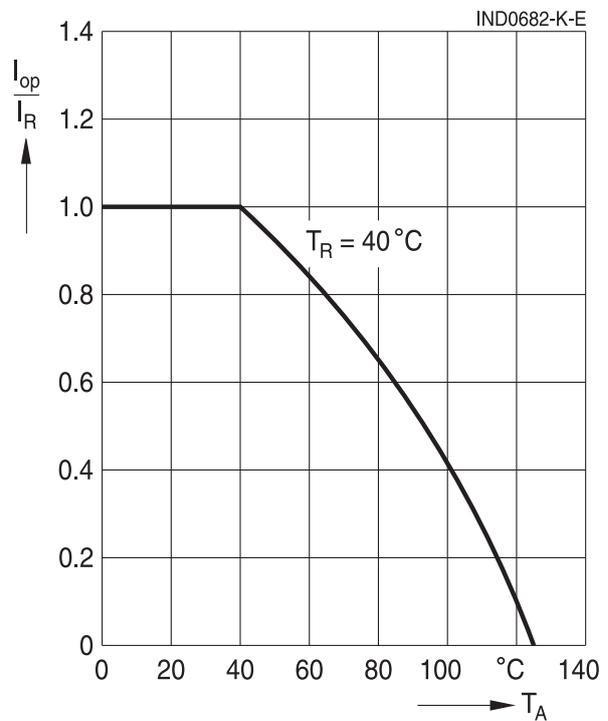
L_N mH	$L_{\text{stray,typ}}$ nH	$I_R^{1)}$ mA	R_{typ} mΩ	V_{test} V DC, 2 s	Ordering code
4.7	300	700	500	750	B82720H0015A016
10	400	600	700	750	B82720H0015A025
28	700	400	1200	750	B82720H0015A028
47	1000	300	2700	750	B82720H0015A030
68	1200	200	3300	750	B82720H0015A035

1)Types with higher rated current on request.

Impedance $|Z|$ versus frequency f
 measured with windings in parallel at +20 °C,
 typical values



Current derating I_{op}/I_R
versus ambient temperature



Cautions and warnings

- Please note the recommendations in our Inductors data book (latest edition), online catalogs and in the data sheets.
 - Particular attention should be paid to the derating curves, if given. Derating applies in the case the ambient temperature in application exceeds the rated temperature of the component.
 - Ensure the operation temperature of the component in application not to exceed the maximum specified value or the upper climatic category temperature.
 - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. It is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.

Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g., ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.
- The following points must be observed if the components are potted, sealed, or varnished in customer applications:
 - Many potting, sealing, or varnishing materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
 - It is necessary to check whether the potting, sealing or varnishing materials used attack or destroy the wire insulation, plastics, or glue.
 - The effect of the potting, sealing, or varnishing materials may change the high-frequency behavior of the components.
- Magnetic core materials such as ferrites are sensitive to direct impact. This can cause the core material to flake or lead to breakage of the magnetic core material.
- Any type of tension or pressure on the product may result in damage and affect its functionality and reliability.
 - The products are only to be attached to fixings or mounting holes provided for this purpose in accordance with the data sheet.
 - If additional mechanical forces are applied to the component, e.g., application of gap pads, it is necessary to check whether they attack or destroy any part of the component.
 - It is not permitted for the product specified in the data sheet to assume a mechanical function in the final application.
- Inductance value can drop if external metallic or magnetic parts will be put close to the coil or into the air gap of the coil or core or magnetic material.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.

Display of ordering codes for TDK Electronics products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications, on the company website, or in order-related documents such as shipping notes, order confirmations and product labels. **The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products.** Detailed information can be found on the Internet under www.tdk-electronics.tdk.com/orderingcodes.

Important notes

The following applies to all products named in this publication:

1. Some parts of this publication contain **statements about the suitability of our products for certain areas of application**. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out **that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application**. As a rule, we are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether a product with the properties described in the product specification is suitable for use in a particular customer application.
2. We also point out that **in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified**. In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or life-saving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.
3. **The warnings, cautions and product-specific notes must be observed.**
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Important notes

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Release 2023-08